

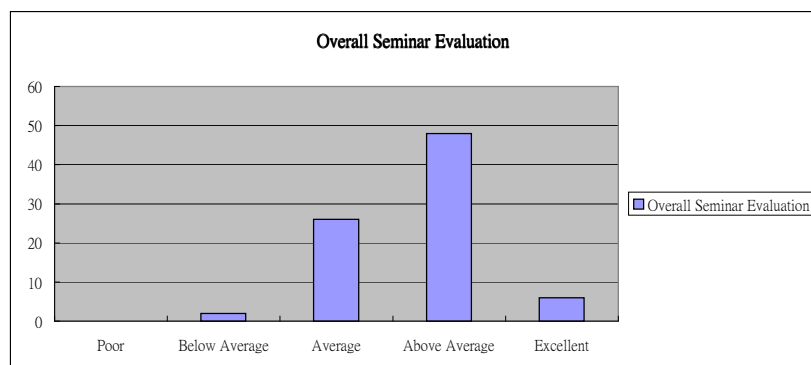
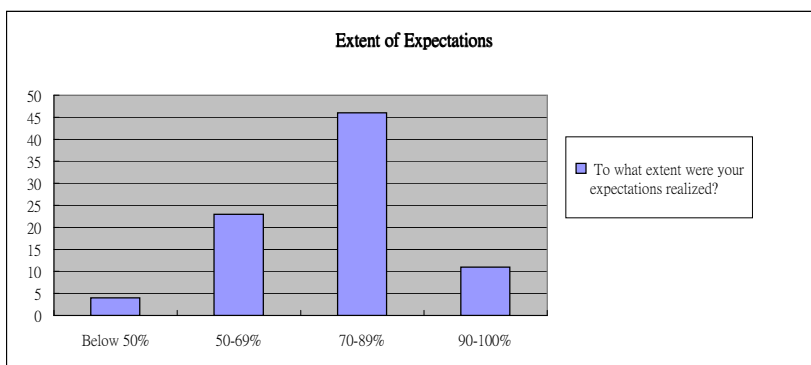
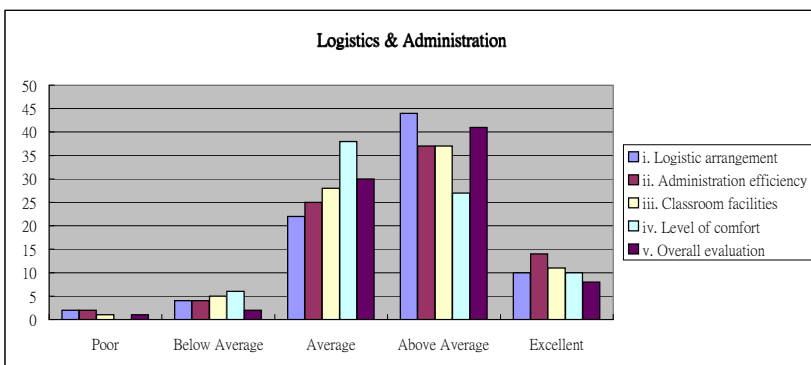
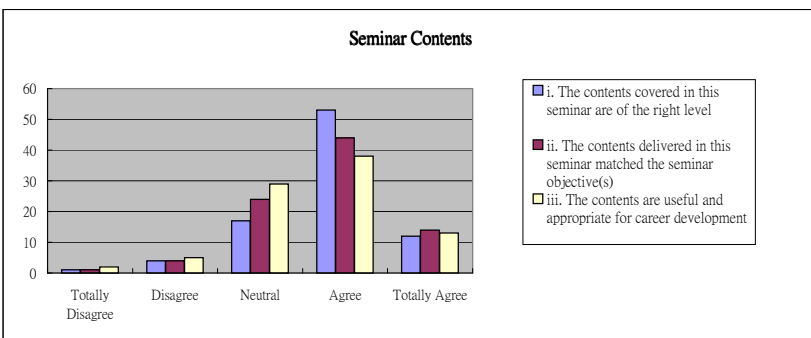
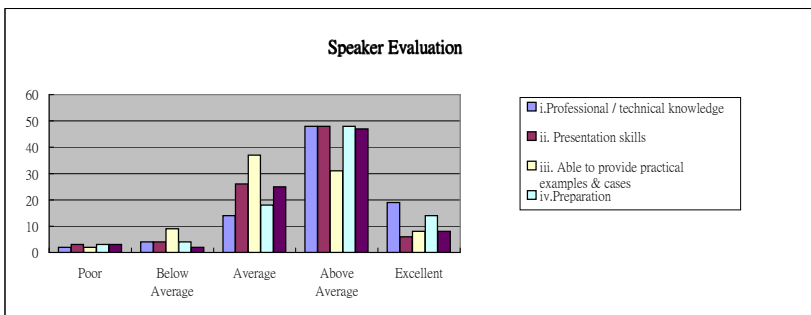
Seminar Evaluation Result

Seminar Title:
 Date of Seminar:
 Number of completed questionnaire =
 Reply rate =

Seminar on PCB & Packaging Technologies

20-Feb-09
87
78%

Overall evaluation on speakers: 92% in total rated "Average", "Above Average" and "Excellent"
 Usefulness of the seminar content: 93% in total rated "Neutral", "Agree" and "Totally Agree"
 Logistic arrangement: 93% in total rated "Average", "Above Average" and "Excellent"
 Extent of Expectation: 95% in total rated above 50% of their expectation
 Overall seminar evaluation: 98% in total rated "Average", "Above Average" and "Excellent"



Evaluation Data

Record frequency count on the table

	1 Poor	2 Below Average	3 Average	4 Above Average	5 Excellent	Total
A Speaker Evaluation						
i. Professional / technical knowledge	2	4	14	48	19	87
ii. Presentation skills	3	4	26	48	6	87
iii. Able to provide practical examples & cases	2	9	37	31	8	87
iv. Preparation	3	4	18	48	14	87
v. Overall evaluation on speakers	3	2	25	47	8	85
Total	13	23	120	222	55	433
			92%			

Record frequency count on the table

	1 Totally Disagree	2 Disagree	3 Neutral	4 Agree	5 Totally Agree	Total
B Contents						
i. The contents covered in this seminar are of the right level	1	4	17	53	12	87
ii. The contents delivered in this seminar matched the seminar	1	4	24	44	14	87
iii. The contents are useful and appropriate for career development	2	5	29	38	13	87
Total	4	13	70	135	39	261
			93%			

Record frequency count on the table

	1 Poor	2 Below Average	3 Average	4 Above Average	5 Excellent	Total
C Logistics & Administration						
i. Logistic arrangement	2	4	22	44	10	82
ii. Administration efficiency	2	4	25	37	14	82
iii. Classroom facilities	1	5	28	37	11	82
iv. Level of comfort	0	6	38	27	10	81
v. Overall evaluation	1	2	30	41	8	82
Total	6	21	143	186	53	409
			93%			

Record frequency count on the table

	Below 50%	50-69%	70-89%	90-100%	Total
D To what extent were your expectations realized?	4	23	46	11	84
Total	4	23	46	11	84
			95%		

Record frequency count on the table

	1 Poor	2 Below Average	3 Average	4 Above Average	5 Excellent	Total
E Overall Seminar Evaluation	0	2	26	48	6	82
Total	0	2	26	48	6	82
			98%			

- A. Speaker Evaluation
vi. Other Comments
- 1) In case the speaker cannot speak fluently English, let her talk in Mandarin or Cantonese.
 - 2) Speaker can use their mother tone, i.e. Putonghua translation if necessary.
 - 3) Should include more practical information instead of only showing some example.

- B. Content
iv. Other topics should be included
- 1) Flexible and Flex/ Rigid PCB fabrication; Assembly technology update; Copper Plating for semiconductor Industry
 - 2) It will be more helpful in a workshop style.
 - 3) Optical waveguides PCB.

- v. Topics should be excluded
- 1) Marketing Information

- C. Logistics & Administration
vi. Other comments
- 1) Adv. IC Package/ Sip & PCB co-design solution. ->it is not a product intro session.

- E. General Comments on the Seminar
- 1) May separate the symposium in two days: one day in PCB Fabrication and Assembly; Second day in IC and Packaging. each Session should by longer- No rush and not missing any important information.
 - 2) The seminar is running in a rush. It is better to split the PCB/ IC Packaging parts into separate days for better understanding of the materials prepared by spee
 - 3) It is practical. We get the general overview of the technologies. It would be better to go in depth with the technologies.